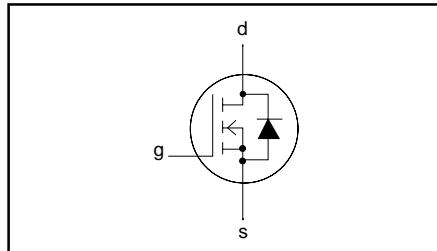


**N-channel TrenchMOS™ transistor****PHX23NQ10T****FEATURES**

- 'Trench' technology
- Low on-state resistance
- Fast switching

**SYMBOL****QUICK REFERENCE DATA**

$$V_{DSS} = 100 \text{ V}$$

$$I_D = 13 \text{ A}$$

$$R_{DS(ON)} \leq 70 \text{ m}\Omega$$

**GENERAL DESCRIPTION**

N-channel enhancement mode field-effect power transistor in a plastic full pack envelope using 'trench' technology.

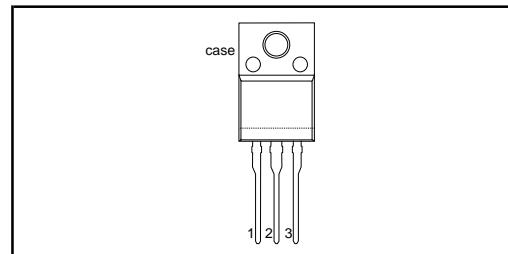
**Applications:-**

- d.c. to d.c. converters
- switched mode power supplies
- T.V. and computer monitor power supplies

The PHX23NQ10T is supplied in the SOT186A (FPAK) conventional leaded package.

**PINNING**

PIN	DESCRIPTION
1	gate
2	drain
3	source
case	isolated

**SOT186A (FPAK)****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DSS}$	Drain-source voltage	$T_j = 25 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}$	-	100	V
$V_{DGR}$	Drain-gate voltage	$T_j = 25 \text{ }^\circ\text{C to } 150 \text{ }^\circ\text{C}; R_{GS} = 20 \text{ k}\Omega$	-	100	V
$V_{GS}$	Gate-source voltage		-	$\pm 20$	V
$I_D$	Continuous drain current	$T_{mb} = 25 \text{ }^\circ\text{C}; V_{GS} = 10 \text{ V}$	-	13	A
		$T_{mb} = 100 \text{ }^\circ\text{C}; V_{GS} = 10 \text{ V}$	-	8	A
$I_{DM}$	Pulsed drain current	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	52	A
$P_D$	Total power dissipation	$T_{mb} = 25 \text{ }^\circ\text{C}$	-	27	W
$T_j, T_{stg}$	Operating junction and storage temperature		-55	150	$^\circ\text{C}$

## N-channel TrenchMOS™ transistor

PHX23NQ10T

**AVALANCHE ENERGY LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$E_{AS}$	Non-repetitive avalanche energy	Unclamped inductive load, $I_{AS} = 14 \text{ A}$ ; $t_p = 100 \mu\text{s}$ ; $T_j$ prior to avalanche = $25^\circ\text{C}$ ; $V_{DD} \leq 25 \text{ V}$ ; $R_{GS} = 50 \Omega$ ; $V_{GS} = 10 \text{ V}$ ; refer to fig:15	-	93	mJ
$I_{AS}$	Peak non-repetitive avalanche current		-	23	A

**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th j-mb}$	Thermal resistance junction to mounting base		-	-	4.6	K/W
$R_{th j-a}$	Thermal resistance junction to ambient	SOT186a package, in free air	-	55	-	K/W

**ELECTRICAL CHARACTERISTICS** $T_j = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}$ ; $I_D = 0.25 \text{ mA}$	100	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ ; $I_D = 1 \text{ mA}$	89 2	- 3	- 4	V
$R_{DS(ON)}$	Drain-source on-state resistance	$V_{GS} = 10 \text{ V}$ ; $I_D = 13 \text{ A}$	$T_j = 150^\circ\text{C}$ $T_j = -55^\circ\text{C}$	1.25 -	- 6	V
$I_{GSS}$	Gate source leakage current	$V_{GS} = \pm 10 \text{ V}$ ; $V_{DS} = 0 \text{ V}$	$T_j = 150^\circ\text{C}$	-	49 115	$m\Omega$ $\text{mA}$
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 100 \text{ V}$ ; $V_{GS} = 0 \text{ V}$	$T_j = 150^\circ\text{C}$	-	10 0.05	$\text{nA}$ $\mu\text{A}$
$Q_{g(\text{tot})}$	Total gate charge	$I_D = 23 \text{ A}$ ; $V_{DD} = 80 \text{ V}$ ; $V_{GS} = 10 \text{ V}$	-	22	-	nC
$Q_{gs}$	Gate-source charge		-	5	-	nC
$Q_{gd}$	Gate-drain (Miller) charge		-	10	-	nC
$t_{d\text{ on}}$	Turn-on delay time	$V_{DD} = 50 \text{ V}$ ; $R_D = 2.2 \Omega$	-	8	-	ns
$t_r$	Turn-on rise time	$V_{GS} = 10 \text{ V}$ ; $R_G = 5.6 \Omega$	-	39	-	ns
$t_{d\text{ off}}$	Turn-off delay time	Resistive load	-	26	-	ns
$t_f$	Turn-off fall time		-	24	-	ns
$L_d$	Internal drain inductance	Measured from drain lead to centre of die	-	4.5	-	nH
$L_s$	Internal source inductance	Measured from source lead to source bond pad	-	7.5	-	nH
$C_{iss}$	Input capacitance	$V_{GS} = 0 \text{ V}$ ; $V_{DS} = 25 \text{ V}$ ; $f = 1 \text{ MHz}$	-	890	1187	pF
$C_{oss}$	Output capacitance		-	139	167	pF
$C_{rss}$	Feedback capacitance		-	83	109	pF

## N-channel TrenchMOS™ transistor

PHX23NQ10T

**REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS** $T_j = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_s$	Continuous source current (body diode)		-	-	13	A
$I_{sm}$	Pulsed source current (body diode)		-	-	92	A
$V_{sd}$	Diode forward voltage	$I_F = 11 \text{ A}; V_{GS} = 0 \text{ V}$	-	0.9	1.2	V
$t_{rr}$	Reverse recovery time	$I_F = 11 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}; V_R = 25 \text{ V}$	-	64	-	ns
$Q_{rr}$	Reverse recovery charge		-	120	-	nC

**ISOLATION LIMITING VALUE & CHARACTERISTIC** $T_{hs} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{isol}$	R.M.S. isolation voltage from all three terminals to external heatsink	$f = 50-60 \text{ Hz};$ sinusoidal waveform; R.H. $\leq 65\%$ ; clean and dustfree	-		2500	V
$C_{isol}$	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	10	-	pF

## N-channel TrenchMOS™ transistor

PHX23NQ10T

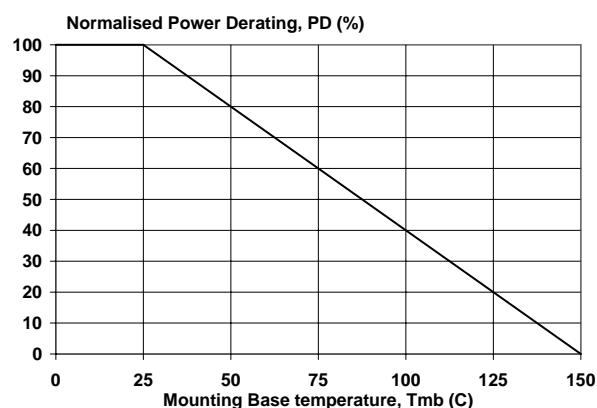


Fig.1. Normalised power dissipation.  
 $PD\% = 100 \cdot P_D / P_{D, 25^\circ C} = f(T_{mb})$

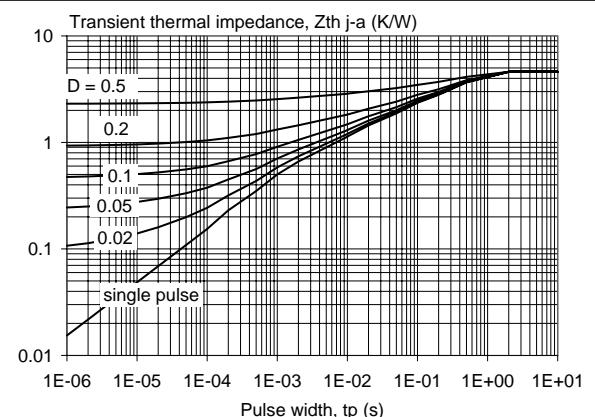


Fig.4. Transient thermal impedance.  
 $Z_{th,j-mb} = f(t_p); \text{parameter } D = t_p/T$

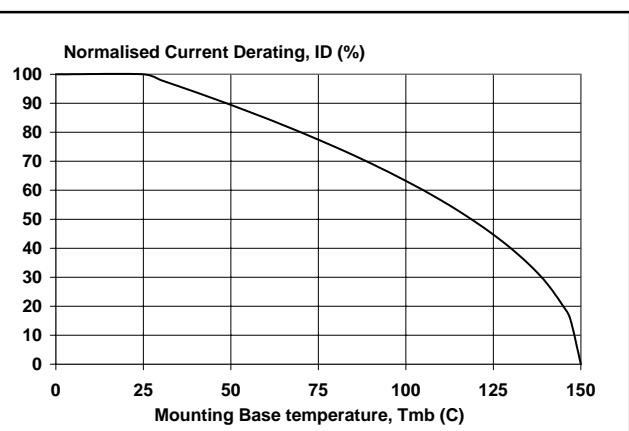


Fig.2. Normalised continuous drain current.  
 $ID\% = 100 \cdot I_D / I_{D, 25^\circ C} = f(T_{mb}); \text{conditions: } V_{GS} \geq 10 \text{ V}$

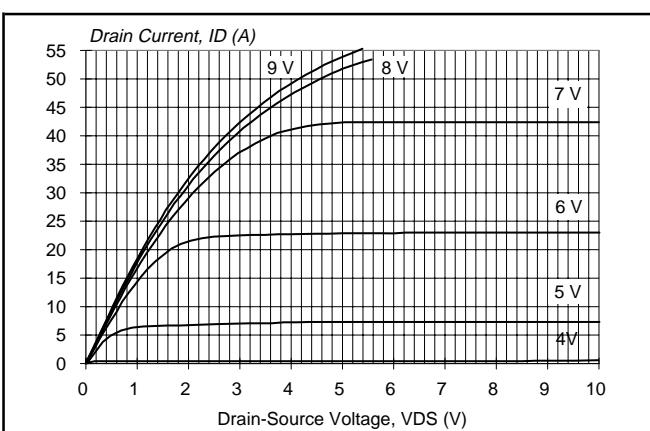


Fig.5. Typical output characteristics,  $T_j = 25^\circ C$ .  
 $I_D = f(V_{DS})$

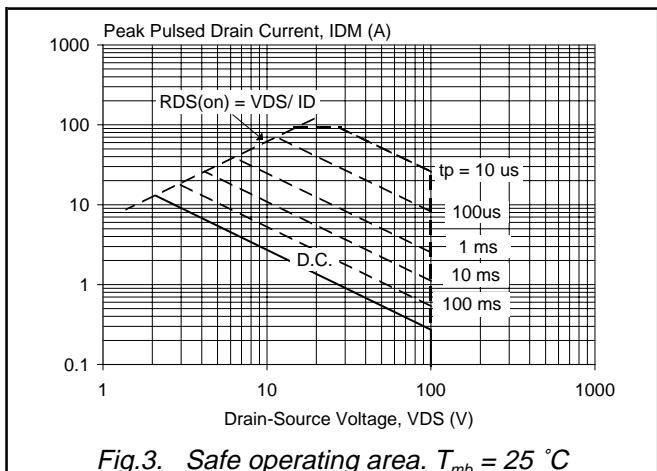


Fig.3. Safe operating area.  $T_{mb} = 25^\circ C$   
 $I_D \& I_{DM} = f(V_{DS})$ ;  $I_{DM}$  single pulse; parameter  $t_p$

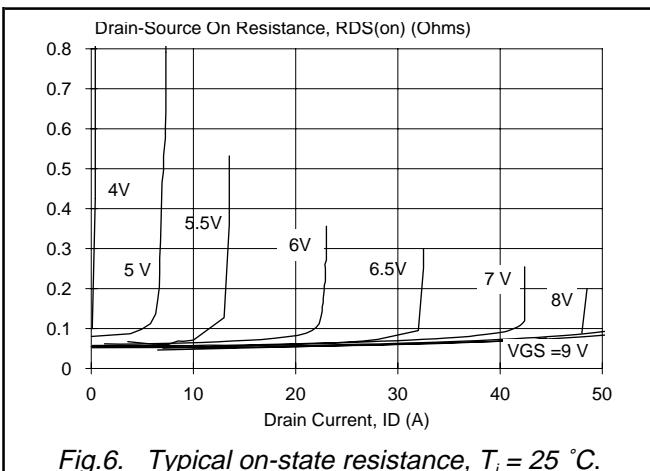


Fig.6. Typical on-state resistance,  $T_j = 25^\circ C$ .  
 $R_{DS(ON)} = f(I_D)$

## N-channel TrenchMOS™ transistor

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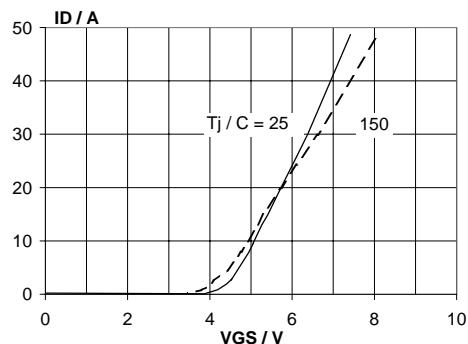


Fig.7. Typical transfer characteristics.  
 $I_D = f(V_{GS})$

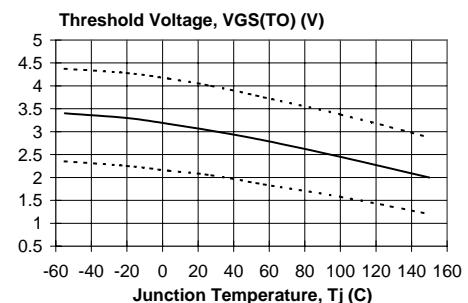


Fig.10. Gate threshold voltage.  
 $V_{GS(TO)} = f(T_j)$ ; conditions:  $I_D = 1 \text{ mA}$ ;  $V_{DS} = V_{GS}$

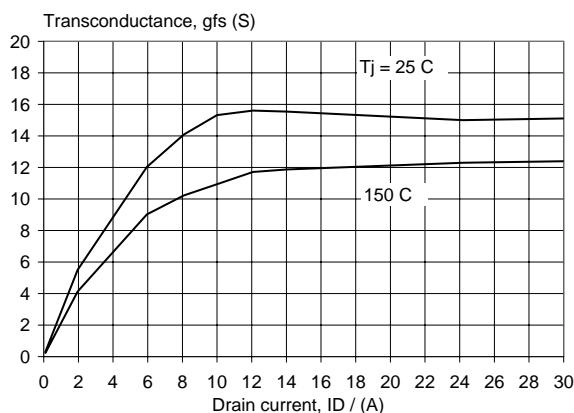


Fig.8. Typical transconductance,  $T_j = 25^\circ C$ .  
 $g_{fs} = f(I_D)$

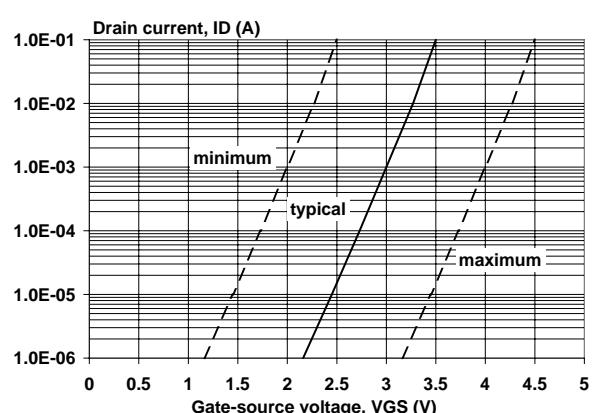


Fig.11. Sub-threshold drain current.  
 $I_D = f(V_{GS})$ ; conditions:  $T_j = 25^\circ C$ ;  $V_{DS} = V_{GS}$

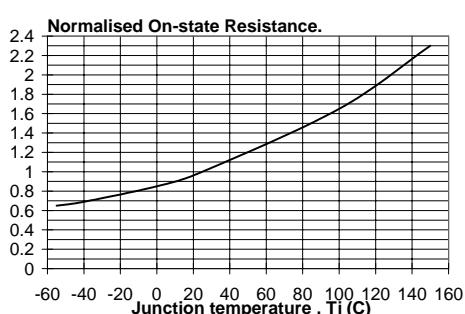


Fig.9. Normalised drain-source on-state resistance.  
 $R_{DS(ON)}/R_{DS(ON)25^\circ C} = f(T_j)$

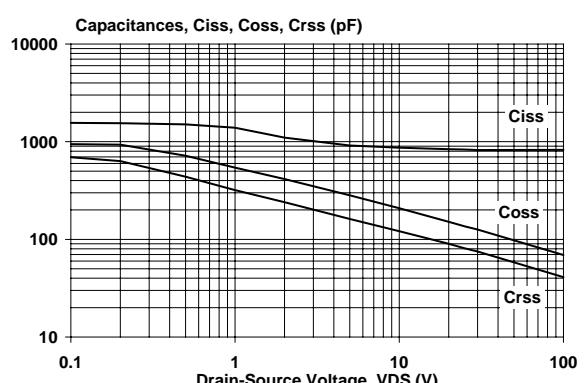


Fig.12. Typical capacitances,  $C_{iss}$ ,  $C_{oss}$ ,  $C_{rss}$ .  
 $C = f(V_{DS})$ ; conditions:  $V_{GS} = 0 \text{ V}$ ;  $f = 1 \text{ MHz}$

## N-channel TrenchMOS™ transistor

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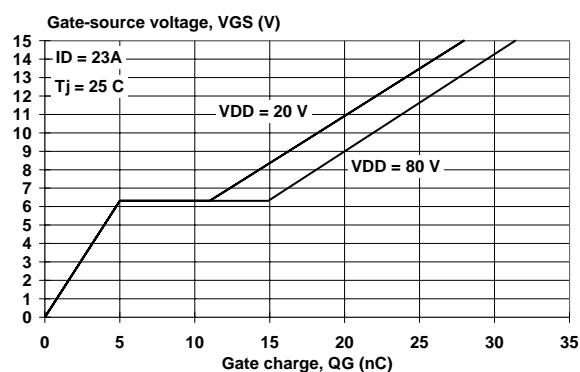


Fig.13. Typical turn-on gate-charge characteristics.  
 $V_{GS} = f(Q_G)$

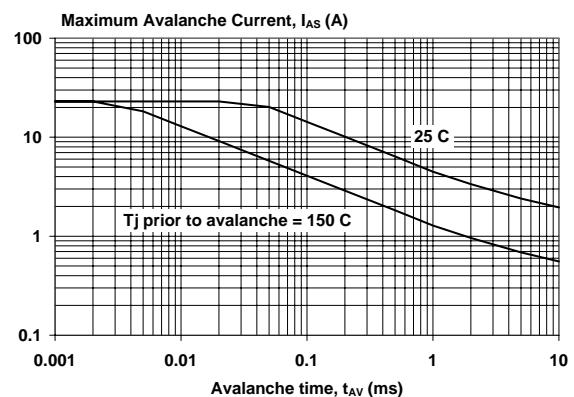


Fig.15. Maximum permissible non-repetitive avalanche current ( $I_{AS}$ ) versus avalanche time ( $t_{AV}$ ); unclamped inductive load

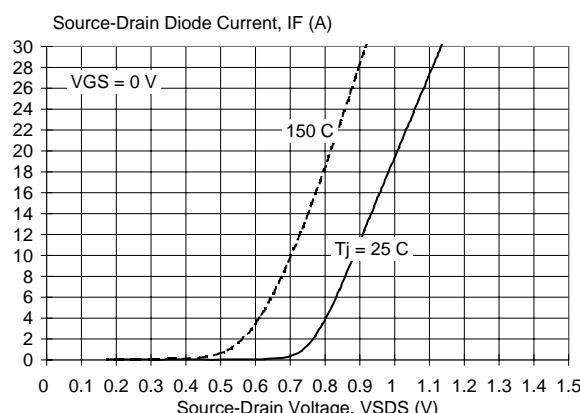


Fig.14. Typical reverse diode current.  
 $I_F = f(V_{SDS})$ ; conditions:  $V_{GS} = 0 \text{ V}$ ; parameter  $T_j$

## N-channel TrenchMOS™ transistor

PHX23NQ10T

## MECHANICAL DATA

Dimensions in mm

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 lead TO-220

SOT186A

Net Mass: 2 g

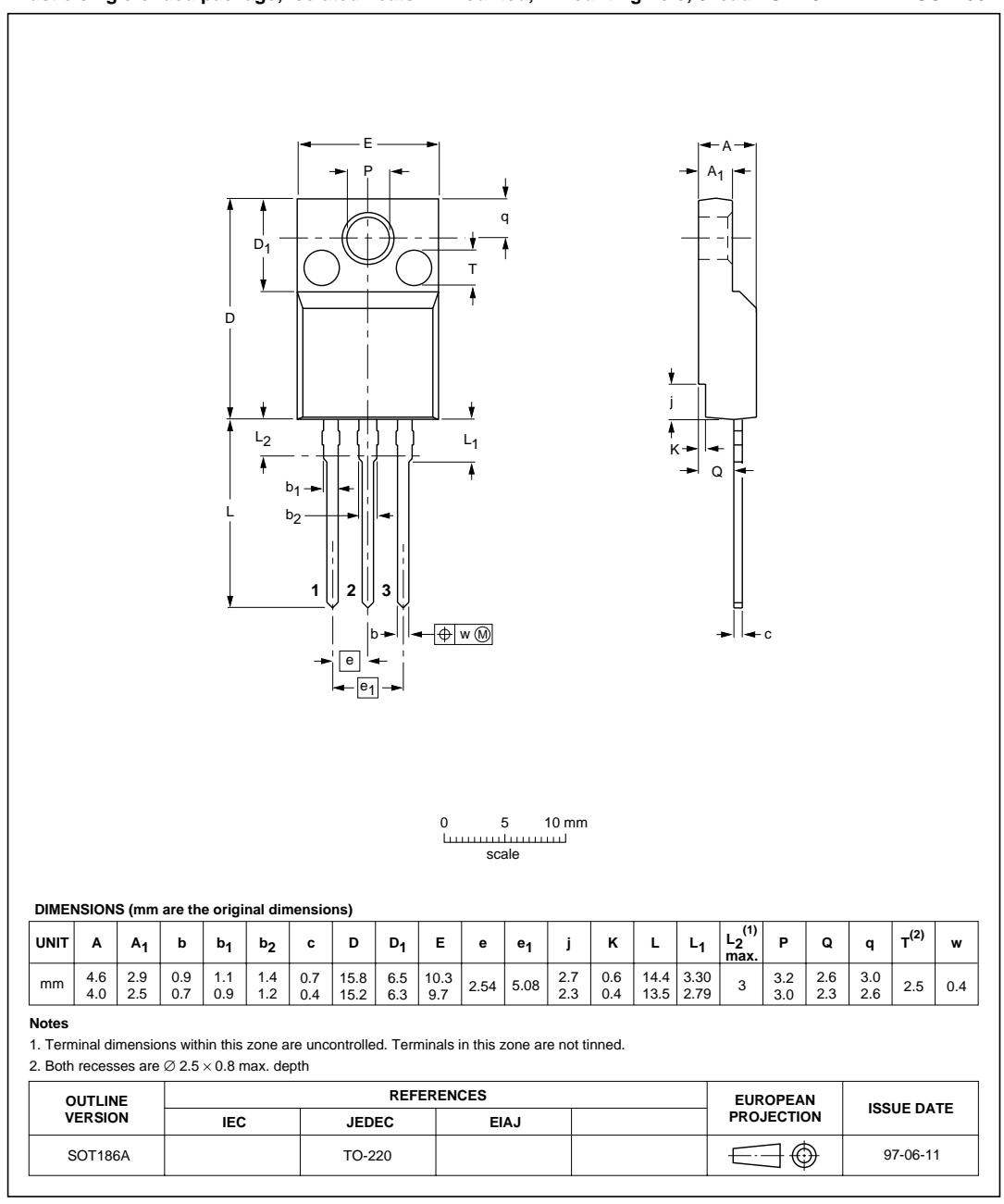


Fig. 16. SOT186A; The seating plane is electrically isolated from all terminals.

## Notes

1. Observe the general handling precautions for electrostatic-discharge sensitive devices (ESDs) to prevent damage to MOS gate oxide.
2. Refer to mounting instructions for F-pack envelopes.
3. Epoxy meets UL94 V0 at 1/8".

**N-channel TrenchMOS™ transistor****PHX23NQ10T****DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
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